

Appl. No. Serial No. 09/714,680
Amdt. dated July 10, 2009
Reply to Office action of April 23, 2009

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. for Reissue No. : 09/714,680
Patent No. : 6,054,198
Applicant : Bunyan *et al.*
Filed : November 16, 2000
Title : Conformal Thermal Interface
Material For Electronic Components

TC/A.U. : 1773
Examiner : S. Ahmed

Docket No. : 2802-257-006

Honorable Commissioner For Patents
Alexandria, VA 22313-1450

AMENDMENT

In response to the Office action of April 23, 2009, reconsideration of the above-identified application as amended is respectfully requested:

Remarks begin on page 2 of this paper.

Attachments: **Consent of Assignee**
Statement Under 37 CFR §3.73(b)
Supplemental Declaration